

EPOXONIC® 376

**Flexible potting compound for
Automotive Engineering,
Microelectronics and Electrical Engineering**

EPOXONIC® 376 is a solvent-free potting compound based on epoxy resin

Main characteristics:

Heat resistance to 150 °C
Thermal shock resistance
Flexibility
Long pot life

Application:

EPOXONIC® 376 is especially suited for low stress potting of pressure sensitive electrical devices with high requirements for thermal shock resistance.

Properties:

Specific values measured by standard test specimen at 23 °C, cured 4 h / 120 °C.

Operating temperature ¹⁾	-40 °C to +150 °C	
Colour	Black	
Shore hardness	50 - 55 Shore A	DIN EN ISO 868
Density	1.1 g/cm ³	DIN EN ISO 1183-1
Glass transition temperature	-45 °C to -35 °C	DIN EN ISO 11357-2
Tensile strength	2.3 MPa	DIN EN ISO 527
E-Modulus	3.5 MPa	DIN EN ISO 527
Elongation at break	80 %	DIN EN ISO 527

1) Depending on the application, other temperature limits may be reasonable

Processing:

Mix ratio		Part A : Part B = 100 : 190 parts by weight = 100 : 210 parts by volume
Viscosity cone/plate viscometer		
	25 °C	2,000 – 4,000 mPas (Part A)
	25 °C	7,000 – 11,000 mPas (Part B)
	25 °C	5,000 – 8,000 mPas (Mixture A + B)
Pot life	25 °C	> 20 h (time to double viscosity, 100g sample)
	60 °C	3 h
Method of application		e.g. dispenser
Cure schedule		e.g. 1 h / 150 °C or 4 h / 120 °C Optimum cure schedules have to be determined by the specific application.

Storage:

The shelf life of EPOXONIC® 376 Part A and Part B is 6 months at temperatures < 25 °C when stored in tightly closed, original containers. Partly emptied containers should be tightly closed immediately after use.

Health and Safety:

Recommended industrial hygiene procedures should always be followed when handling this product. Please refer to the corresponding Material Safety Data Sheet for details.

Packaging:

EPOXONIC® 376 Part A and Part B are delivered in metal cans.
Other packaging options are available upon request.

Quality Assurance:

If required EPOXONIC® 376 will be supplied with a Certificate of Analysis.

Disclaimer:

All information herein is based on the present state of knowledge and believed to be reliable. Any suggestions or recommendations are made without liability on our part since we shall have no control over the use of our product. Buyers and users should make their own assessment of this product under their own conditions and for their own requirements.